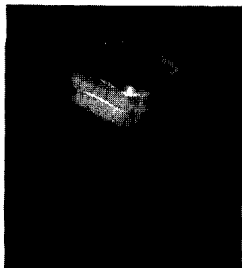


VTP Process Photodiodes

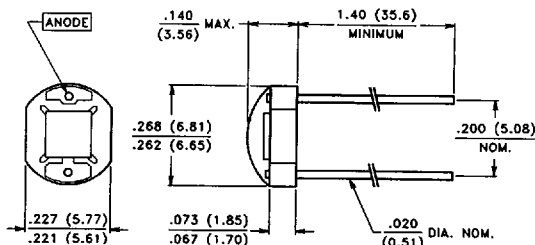
VTP8350, 50S, 51

E G & G VACTEC

T-41-51



PACKAGE DIMENSIONS Inch (mm)



PRODUCT DESCRIPTION

Planar silicon photodiode mounted on a two lead ceramic substrate and coated with a thick layer of clear epoxy. These diodes exhibit low dark current under reverse bias and fast speed of response.

CASE 11 CERAMIC

CHIP ACTIVE AREA: .012 in² (7.45 mm²)

ABSOLUTE MAXIMUM RATINGS

Storage Temperature: -20°C to 75°C

Operating Temperature: -20°C to 75°C

ELECTRO-OPTICAL CHARACTERISTICS @ 25°C (See also VTP curves, pages 48-49)

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VTP8350			VTP8350S			VTP8351			UNITS
			Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
I _{sc}	Short Circuit Current	H = 100 fc, 2850 K	65	80		80		65	80		μA	
TC I _{sc}	I _{sc} Temp. Coefficient	2850 K		.20		.20		.20			% / °C	
V _{oc}	Open Circuit Voltage	H = 100 fc, 2850 K		350		350		350			mV	
TC V _{oc}	V _{oc} Temp. Coefficient	2850 K		-2.0		-2.0		-2.0			mV / °C	
I _D	Dark Current	H = 0, V _R = 50 V		30 ■		—		18			nA	
R _{sh}	Shunt Resistance	H = 0, V = 10 mV		100		50	100		100		MΩ	
C _J	Junction Capacitance	H = 0, V = 3 V		50		120 ■		24 ■			pF	
R _e	Responsivity	940 nm		.06		.04	.06		.06		A/(W/cm ²)	
S _R	Sensitivity	@ Peak		.55		.55		.55			A/W	
λ _{range}	Spectral Application Range		400		1150	400		1150	400		1150	nm
λ _p	Spectral Response - Peak			925		925		925			925	nm
V _{BR}	Breakdown Voltage		33	140		50	140		50	140		V
θ _{1/2}	Ang. Resp. - 50% Resp. Pt.			±60		±60		±60			±60	Degrees
NEP	Noise Equivalent Power			1.8 x 10 ⁻¹³ (Typ.)		1.8 x 10 ⁻¹³ (Typ.)		1.4 x 10 ⁻¹³ (Typ.)				W/√Hz
D*	Specific Detectivity			1.5 x 10 ¹² (Typ.)		1.5 x 10 ¹² (Typ.)		2.0 x 10 ¹² (Typ.)				cm ² √Hz/W

■ V_R = 10 V ■ V = 0 V ■ V = 15 V